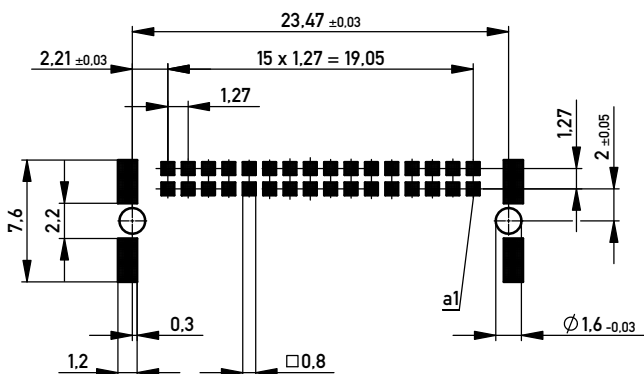


Leiterplatten-Layout Vorschlag für SMT  
PCB-Layout Proposal for SMT



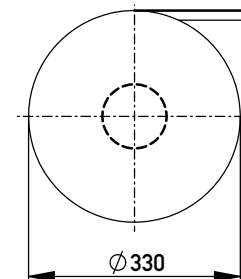
Anforderungsstufe 1  
Performance Level 1

Kontaktbereich vergoldet  
Mating Area gold plating

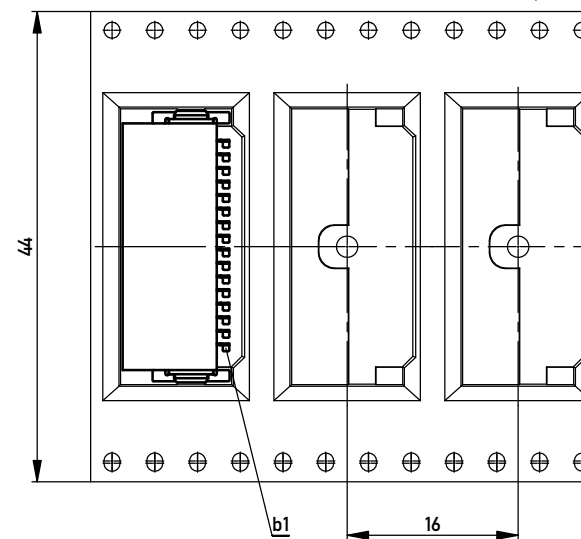
Anschlussbereich verzinkt 4-6 µm  
Terminal Area 4-6 µm tin plating

Koplanarität der Anschlüsse ≤ 0.1 mm  
Coplanarity Area of Termination ≤ 0.1 mm

Verpackt im Gurt nach DIN IEC 60286-3  
Tape on Reel Packaging according to DIN IEC 60286-3  
Verpackungseinheit: 560 Stück  
Packaging unit: 560 pcs



Abspulrichtung - Reel off Direction



BA7-03 - Standard Bauhöhe  
type7-03 - Standard Assembly Height

Information:		Tolerances	 All Dimensions in mm	Scale 3:1
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www.ERNI.com		<b>354096</b>		I <b>A3</b>
c	25.06.2015	Class		SMCB
Index	Date			

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